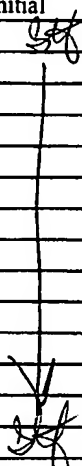



Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No. MAT-9 Applicants: Timans et al Filing Date July 28, 2003	Serial No.: 10/629,400 Group 2812
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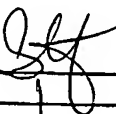


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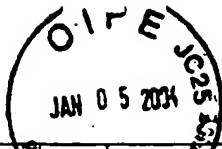
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	B	4,579,080	4/1/1986	Martin et al			
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Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
	O	WO 03/060447 A1	7/24/2003	Canada			Yes	No

Other Documents

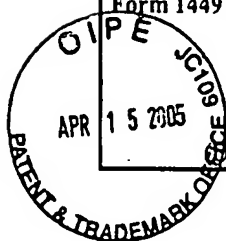
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Form 1449 (Modified)	Atty Docket No. MAT-9	Serial No.: 10/629,400
Information Disclosure Statement By Applicant	Applicants: Timans et al	Group 3742
(Use Several Sheets if Necessary)	Filing Date July 28, 2003	



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<i>JS</i>		5,960,158	9/28/1999	Gat et al			

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Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
				Canada			Yes	No

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
Examiner	Date Considered	
<i>Shawntina Inguva</i>	<i>5/20/05</i>	

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

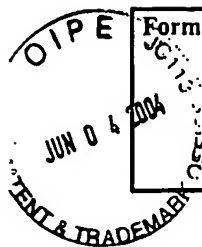
A circular stamp from the Office of Intellectual Property (OIP). The text "OIP" is at the top, "JUN 22 2004" is in the center, and "PATENT & TRADEMARK OFFICE" is at the bottom. A rectangular stamp "JC113" is partially visible on the right side.

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
<i>ghe</i>		6,067,931	5/30/2000	Ghezze et al	—	—	

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							Yes	No
				Canada				

Other Documents		
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Information Disclosure Statement By Applicant	Applicants: Timans et al	
(Use Several Sheets if Necessary)	Filing Date July 28, 2003	Group 2812

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				Canada			Yes	No

Other Documents

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Examiner <i>Shawntina Igua</i>		Date Considered <i>5/20/05</i>

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